



US00D812241S

(12) **United States Design Patent** (10) **Patent No.:** **US D812,241 S**
LiCalzi et al. (45) **Date of Patent:** **** Mar. 6, 2018**

(54) **INSTRUMENT MODULE**

D685,483 S * 7/2013 LiCalzi D24/216
D735,878 S * 8/2015 Chang D24/216
D738,243 S * 9/2015 Selberg D10/81
D740,955 S 10/2015 Gutmann et al.

(71) Applicant: **Siemens Healthcare Diagnostics Inc.**,
Tarrytown, NY (US)

FOREIGN PATENT DOCUMENTS

(72) Inventors: **Daniel LiCalzi**, New York, NY (US);
Scott Salmon, Tenafly, NJ (US); **Josh Hartl**, Philadelphia, PA (US)

JP 1517913 S 2/2015
WO DM081998 4/2014

(73) Assignee: **Siemens Healthcare Diagnostics Inc.**,
Tarrytown, NY (US)

* cited by examiner

Primary Examiner — Wan Laymon
Assistant Examiner — Mark Booker

(**) Term: **15 Years**

(57) **CLAIM**

(21) Appl. No.: **29/569,389**

The ornamental design for an instrument module, as shown and described.

(22) Filed: **Jun. 27, 2016**

DESCRIPTION

(51) **LOC (11) Cl.** **24-01**

(52) **U.S. Cl.**
USPC **D24/216**

(58) **Field of Classification Search**
USPC D24/216, 111, 127, 107, 169, 186, 217,
D24/219, 223–224, 231–234; D10/46,
D10/70, 81, 97; 422/1, 62–65, 67, 68.1,
422/70, 81, 129, 500, 506, 561,
422/FOR. 106; 435/287.1, 287.3;
436/43, 45, 47; 600/300, 301, 368, 372,
600/481, 529, 544, 554, 561; 607/4, 5, 9,
607/30
CPC ... G01R 31/31907; B04B 13/00; B04B 15/00;
B04B 2005/0435; B04B 5/0421; A61B
5/157; G06F 19/366; B01D 21/262
See application file for complete search history.

FIG. 1 is a front perspective view of an instrument module in accordance with an embodiment;
FIG. 2 is a rear perspective view of an instrument module in accordance with an embodiment;
FIG. 3 is a front elevational view of an instrument module in accordance with an embodiment;
FIG. 4 is a rear elevational view of an instrument module in accordance with an embodiment;
FIG. 5 is a left side elevational view of an instrument module in accordance with an embodiment;
FIG. 6 is a right side elevational view of an instrument module in accordance with an embodiment;
FIG. 7 is a top view of an instrument module in accordance with an embodiment; and,
FIG. 8 is a bottom view of an instrument module in accordance with an embodiment.

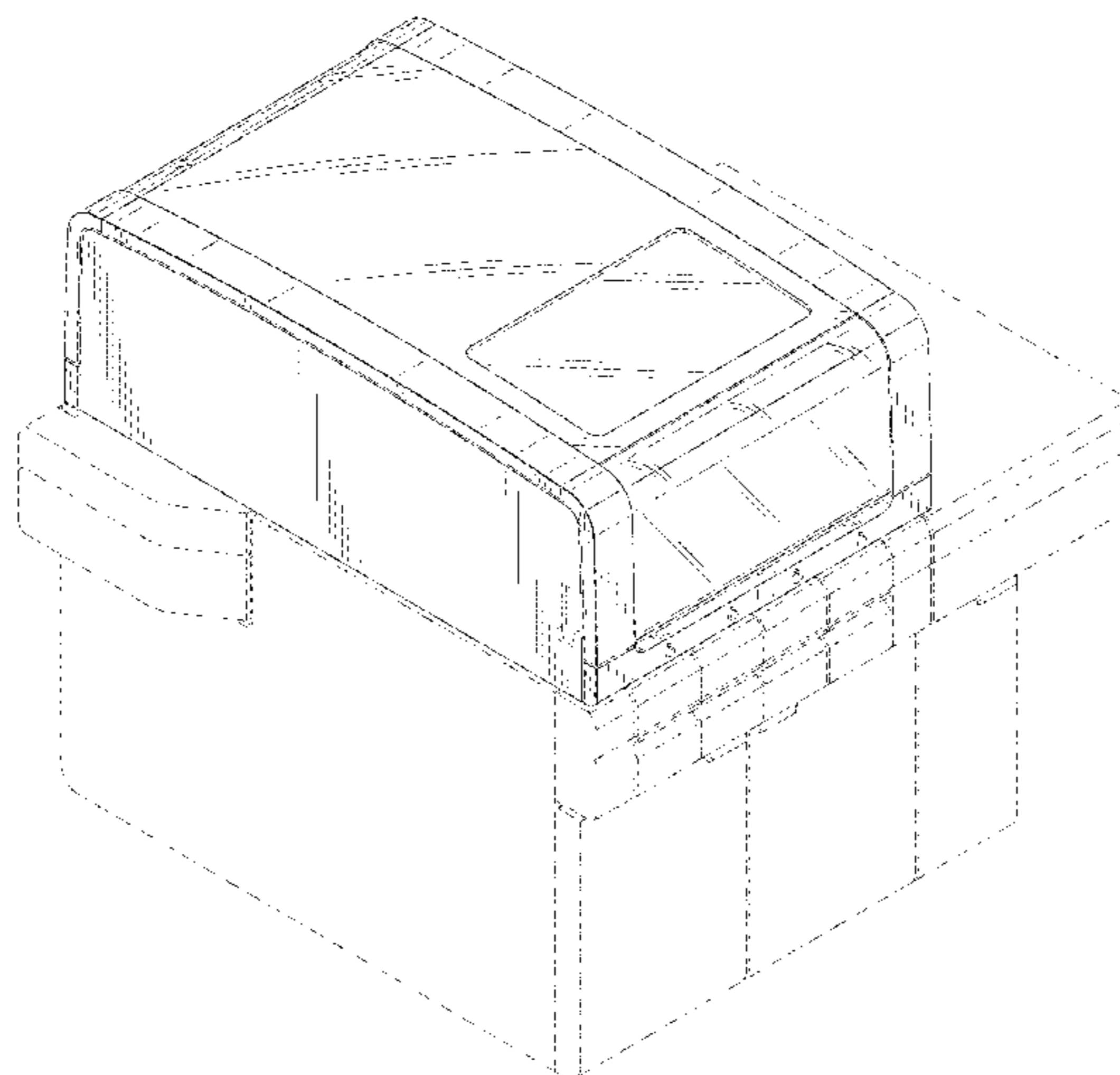
(56) **References Cited**

U.S. PATENT DOCUMENTS

D645,367 S * 9/2011 Hayashi D10/81
D669,189 S * 10/2012 Liu D24/216
D676,143 S * 2/2013 Liu D24/216
D676,568 S * 2/2013 Liu D24/216

The broken lines shown in the figures represent portions of the instrument module that form no part of the claimed design. The broken line showing immediately adjacent the shaded areas represents boundaries to the claimed design and forms no part of the claimed design.

1 Claim, 8 Drawing Sheets



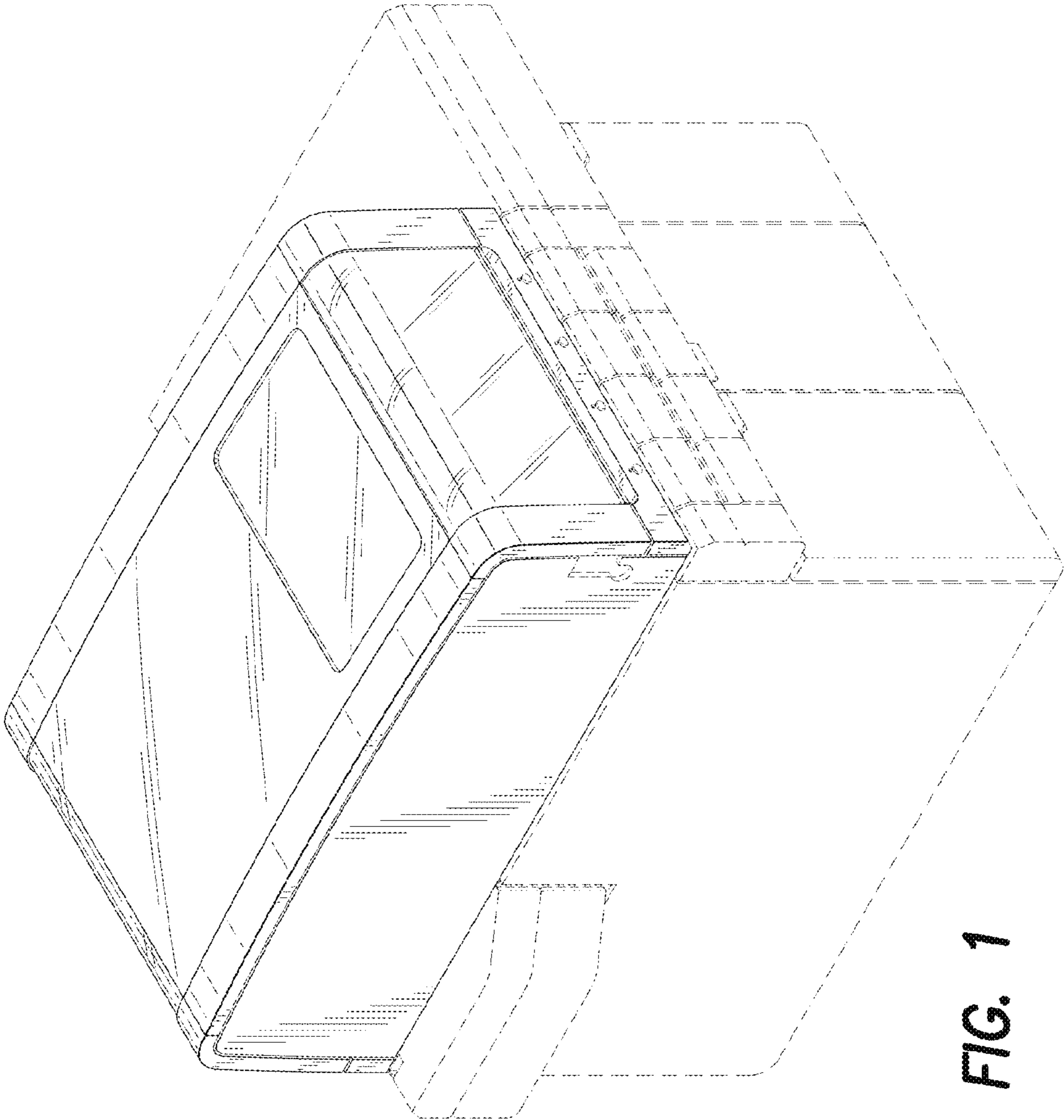


FIG. 1

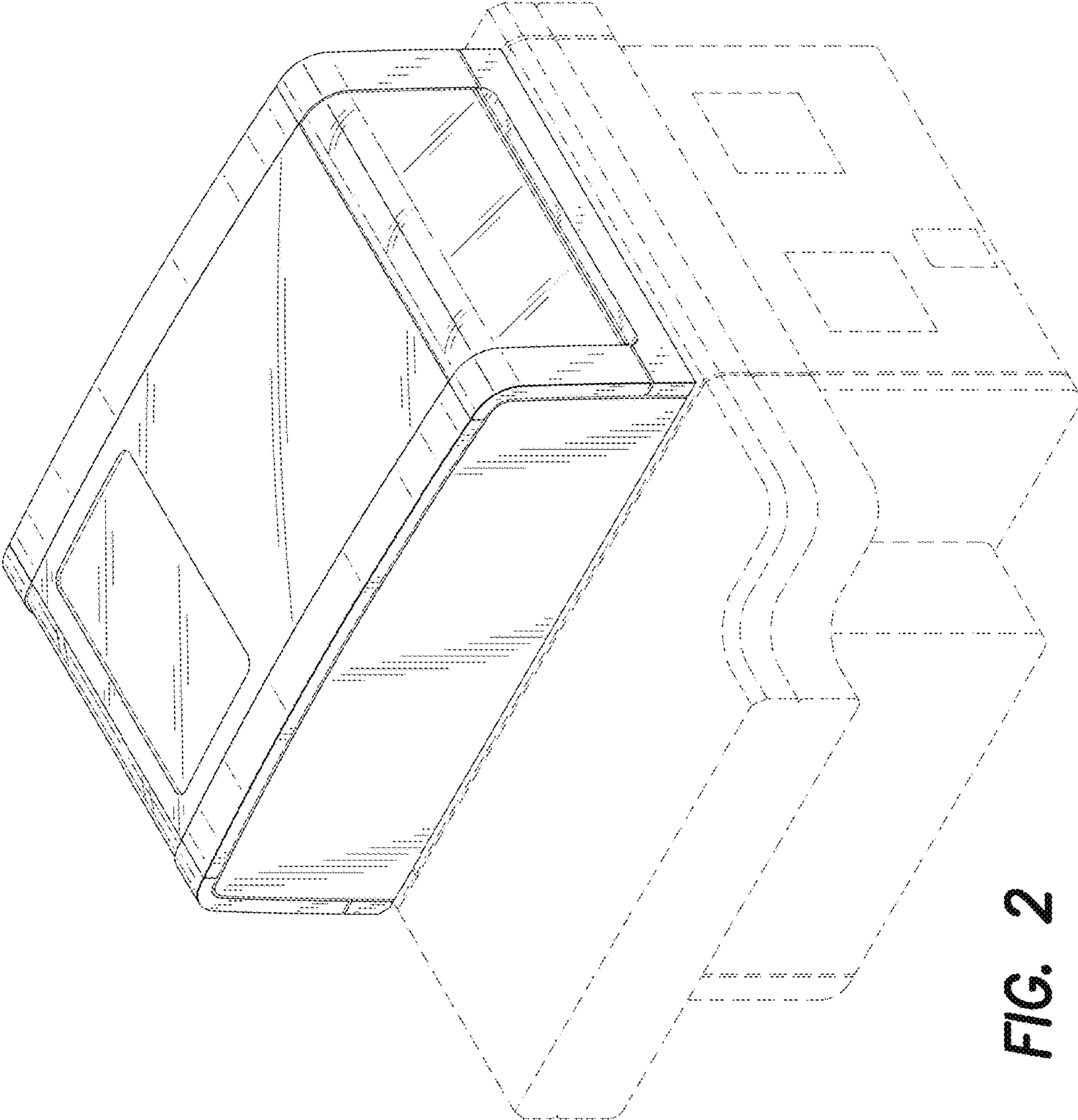


FIG. 2

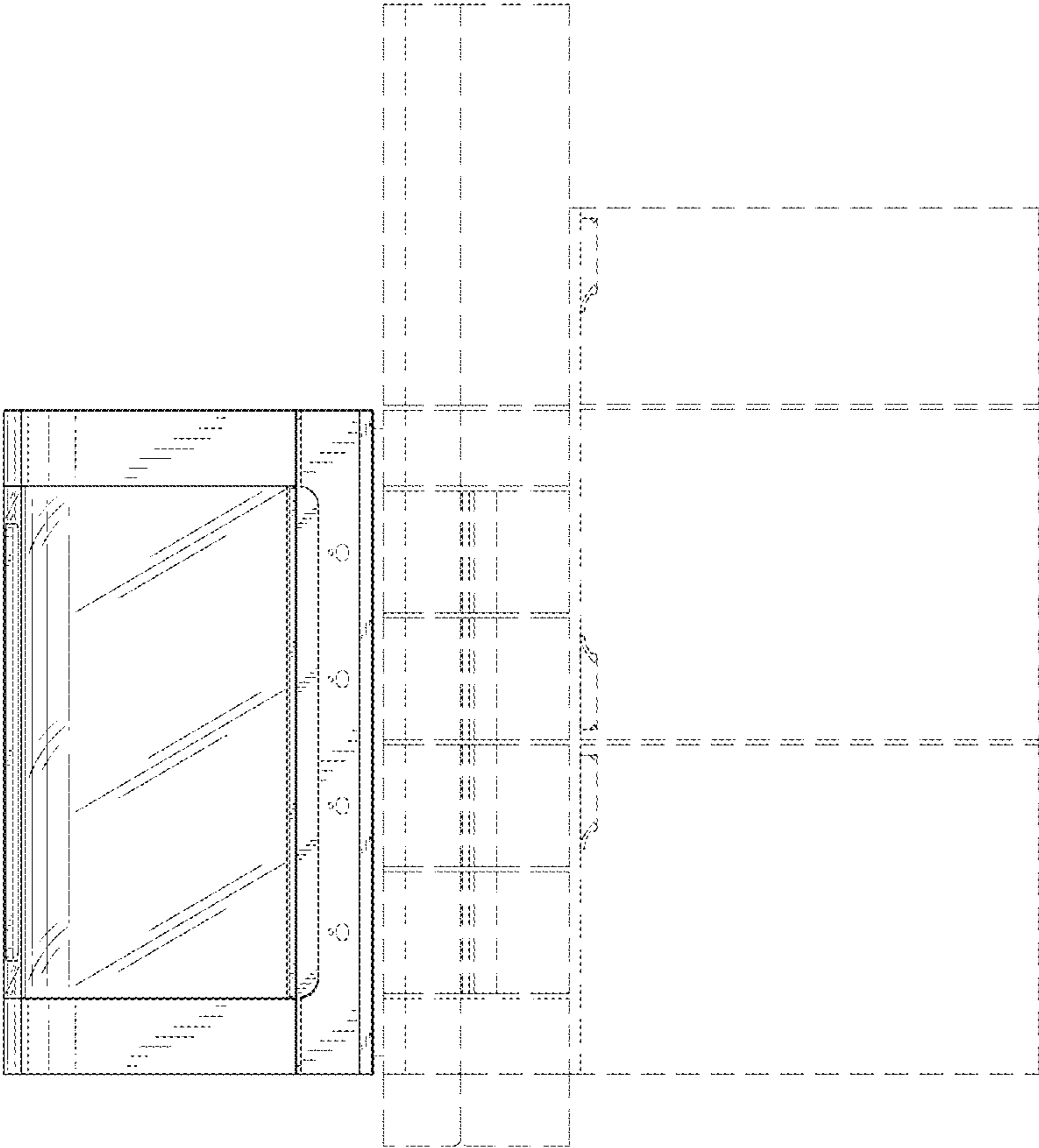


FIG. 3

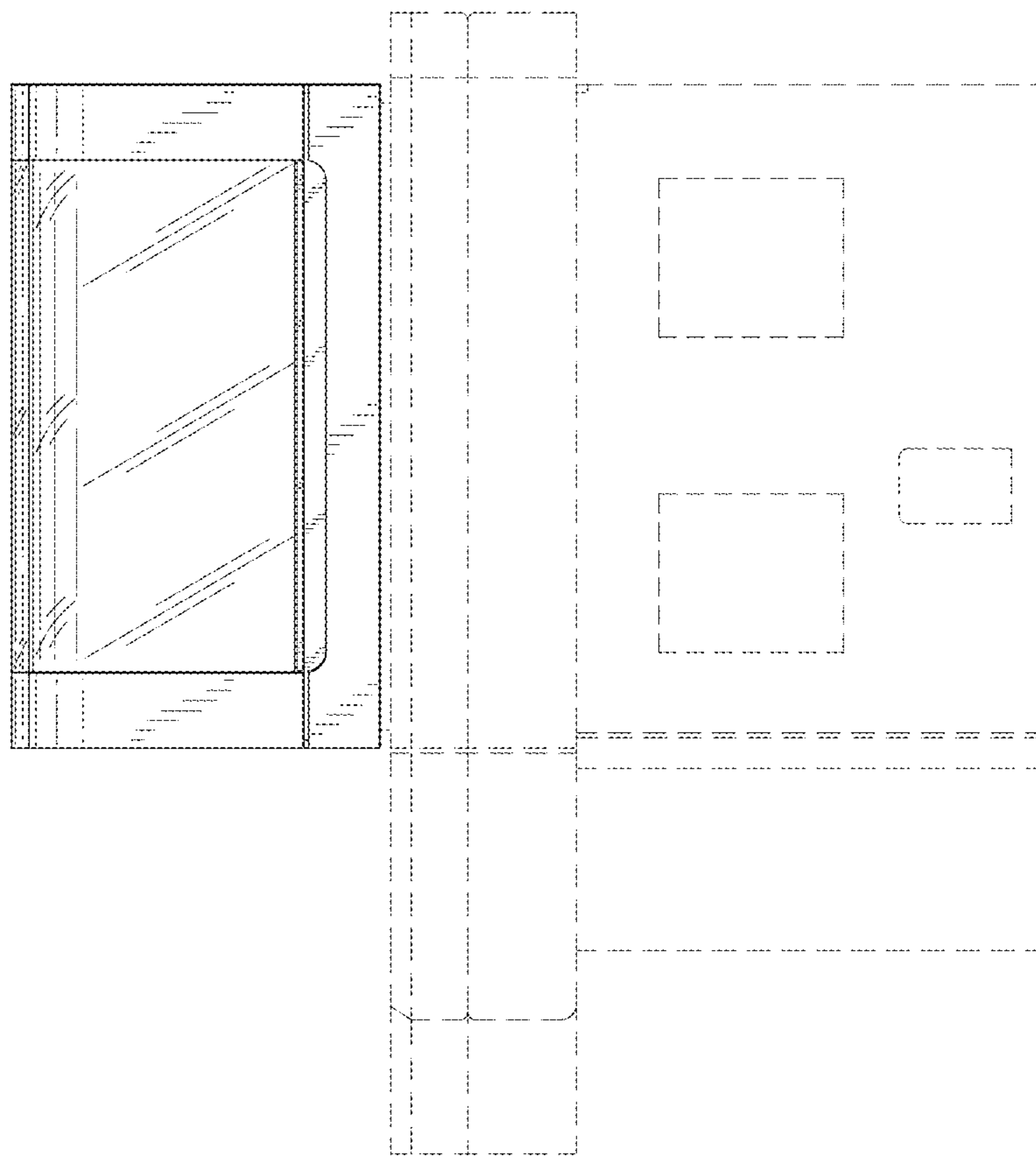


FIG. 4

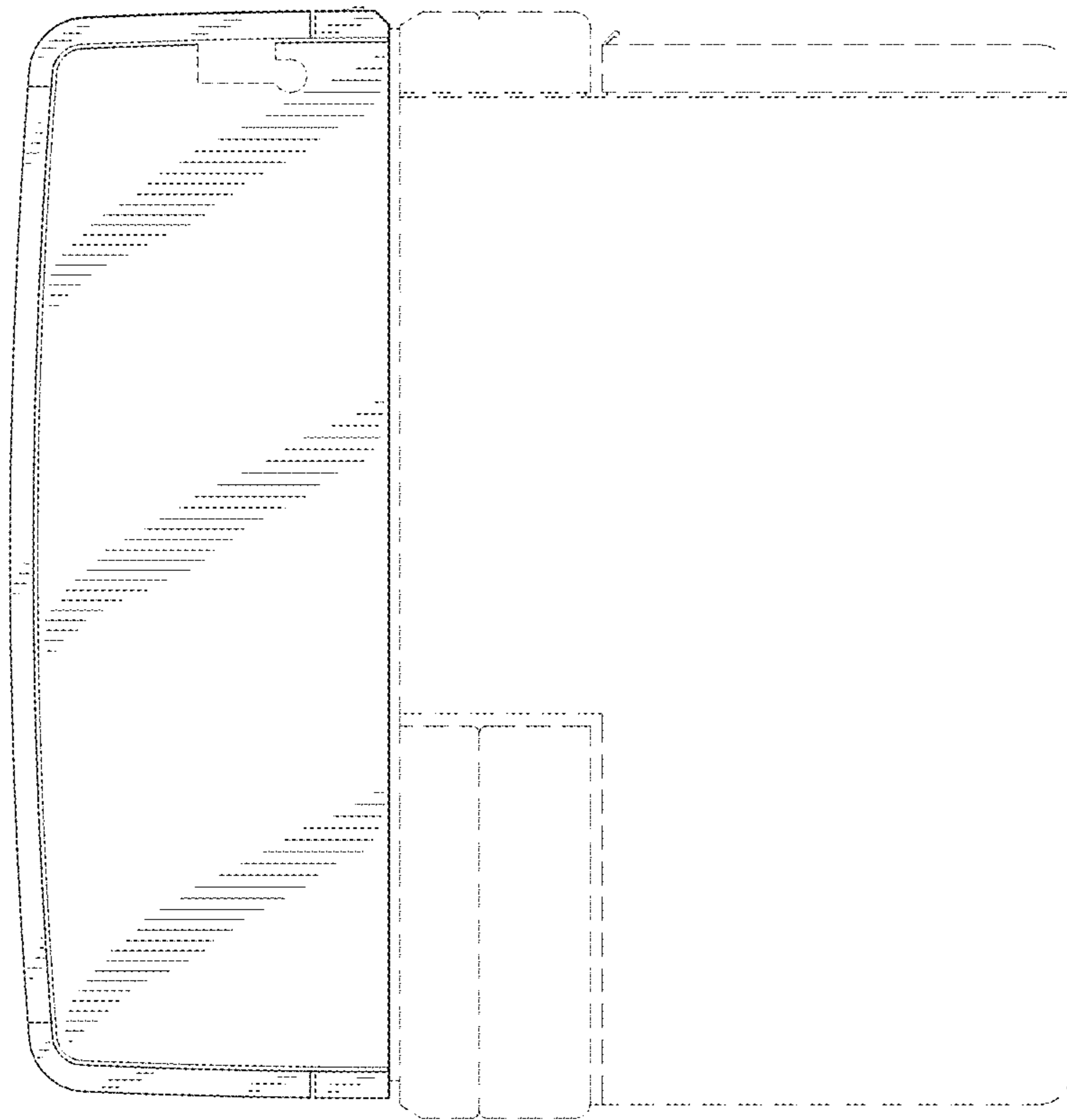


FIG. 5

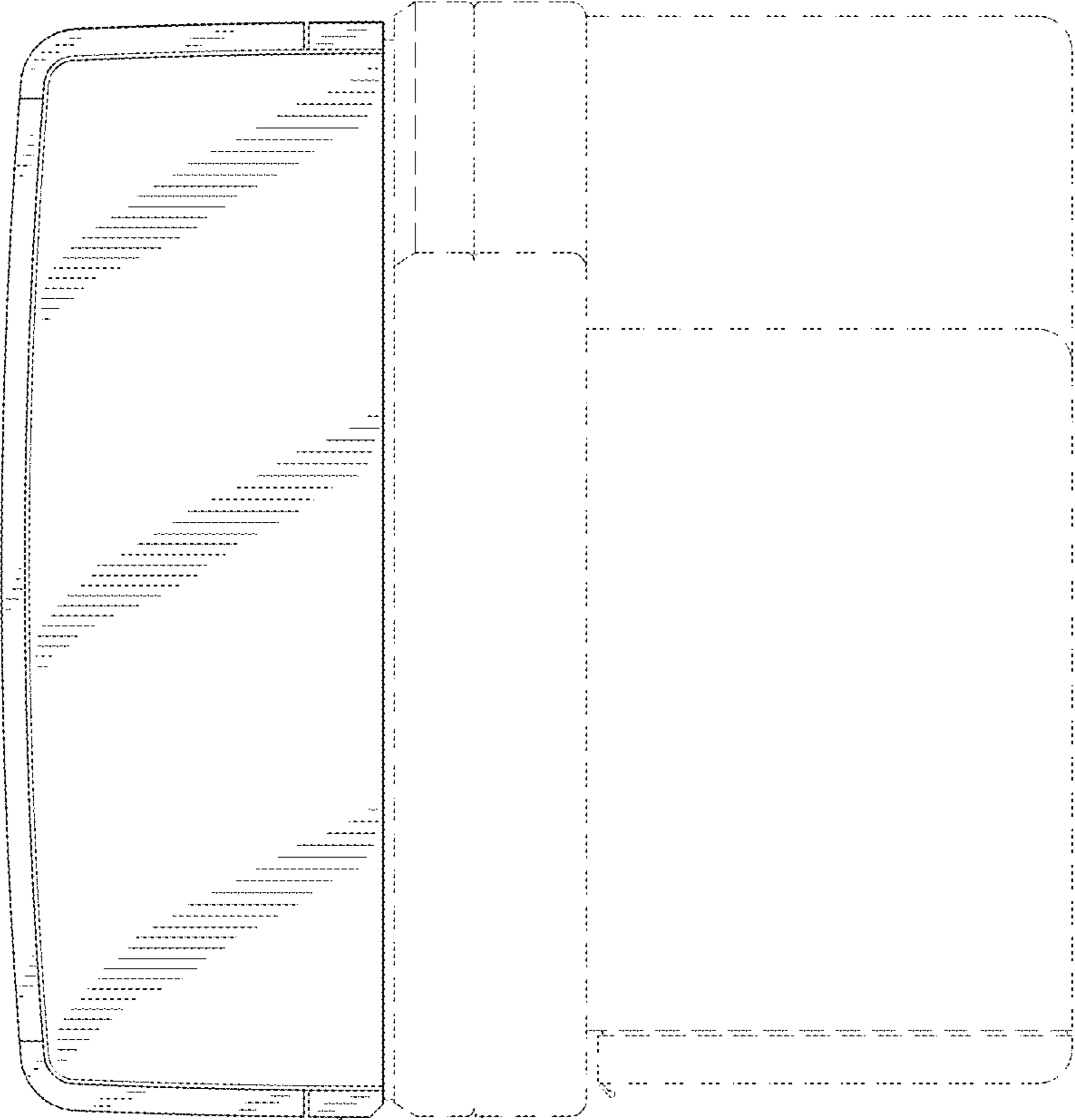


FIG. 6

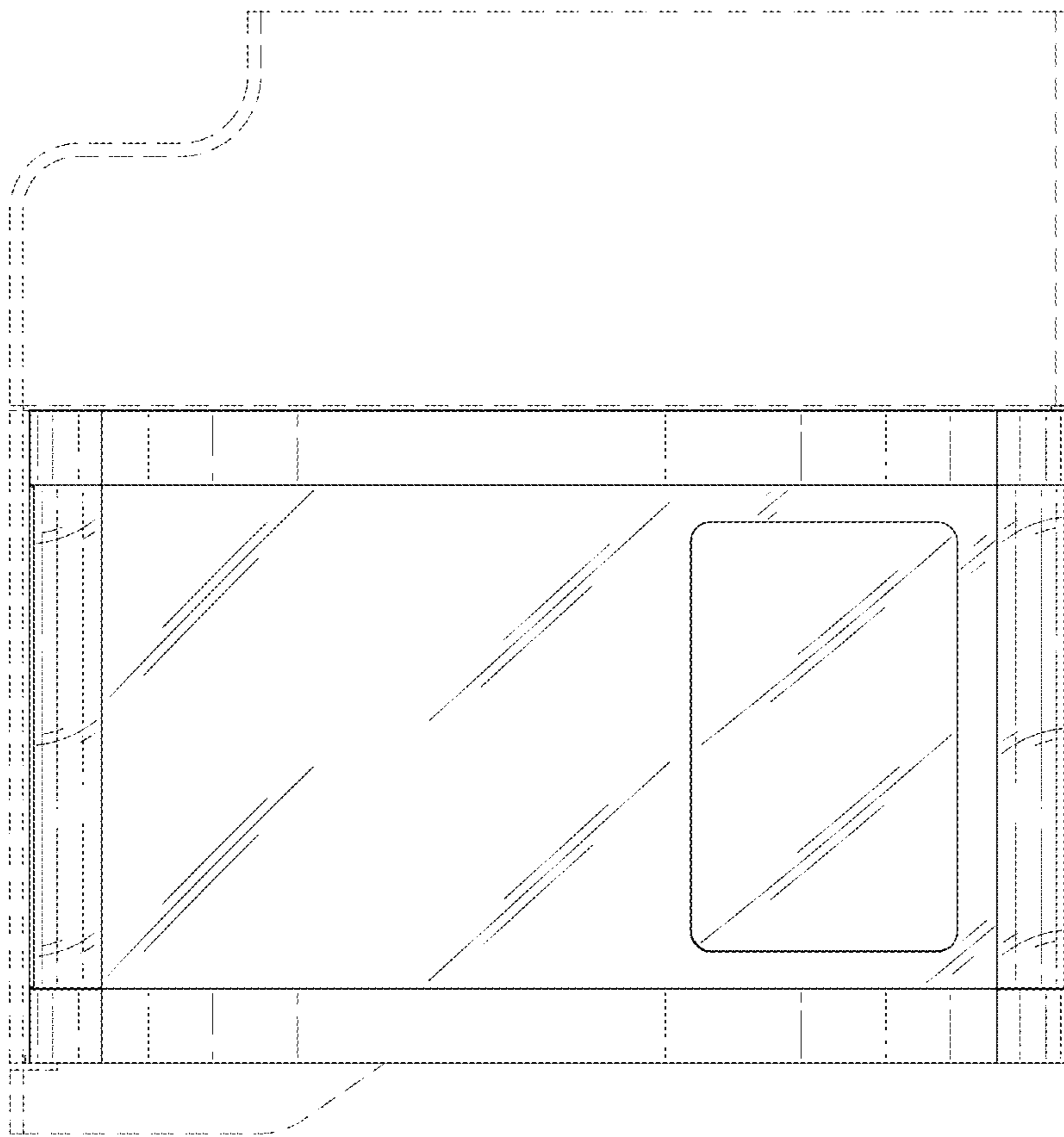


FIG. 7

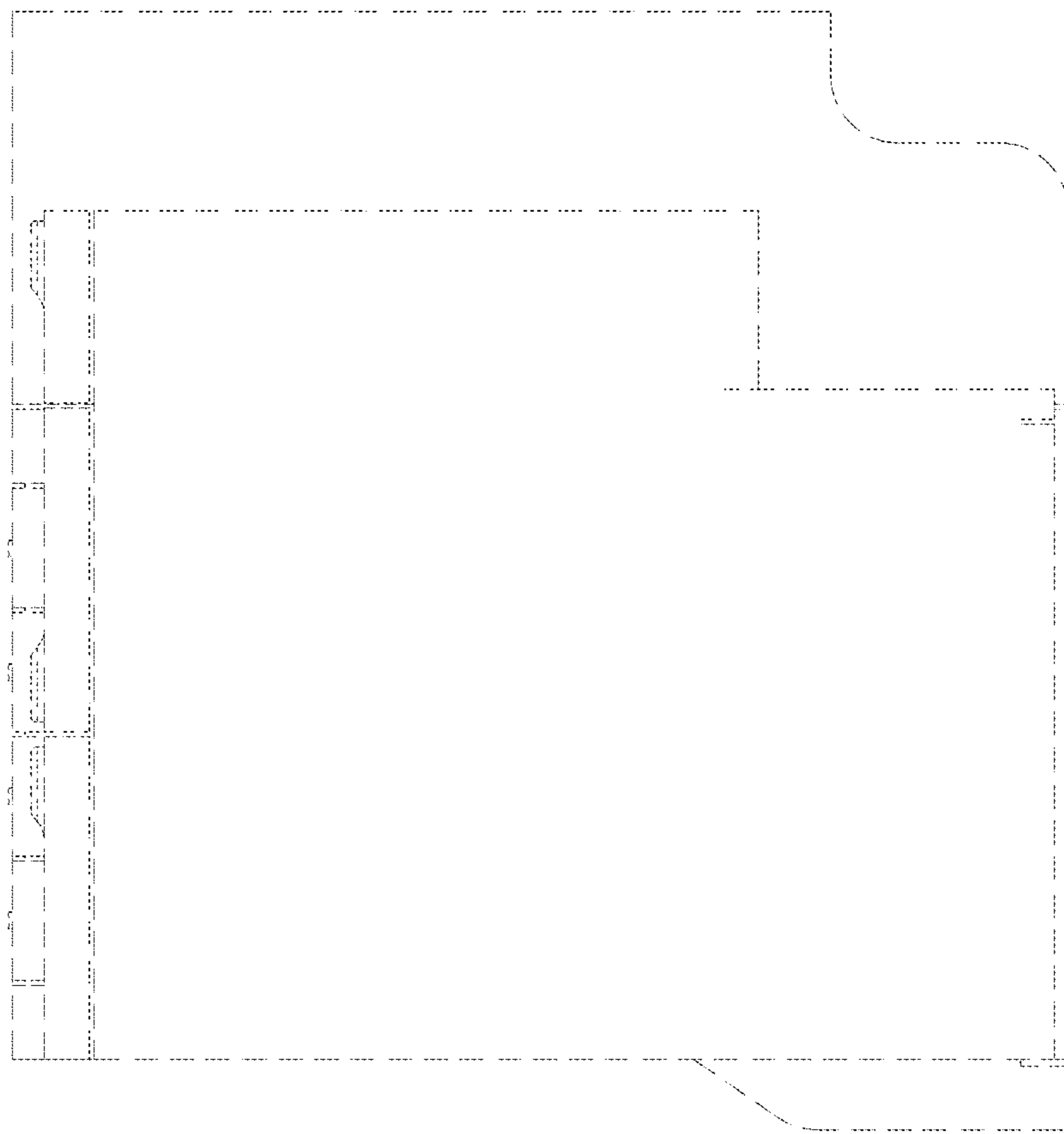


FIG. 8